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- 8-Bit Serial-In, Parallel-Out Shift
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Shift Register Has Direct Clear

(TOP VIEW) Q_B 16**∏** V_{CC} Q_C [15 Q_A Q_D [] 3 14 SER 13 OE Q_{E} Q_F [12 RCLK Q_G L 11 SRCLK 10 SRCLR Q_H [] 9∏ Q_{H′} GND [

DW, E, M, NS, OR SM PACKAGE

description/ordering information

The CD74HC595 device contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for both the shift and storage registers. The shift register has a direct overriding clear (SRCLR) input, serial (SER) input, and serial output for cascading. When the output-enable (OE) input is high, the outputs are in the high-impedance state.

Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

ORDERING INFORMATION

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube of 25	CD74HC595E	CD74HC595E
	SOIC - DW	Tube of 40	CD74HC595DW	LICEOEM
	SOIC - DW	Reel of 2000	CD74HC595DWR	HC595M
		Tube of 40	CD74HC595M	
−55°C to 125°C	SOIC - M	Reel of 2500	CD74HC595M96	HC595M
		Reel of 250	CD74HC595MT	
	SOP – NS	Reel of 2000	CD74HC595NSR	HC595M
	SSOP – SM	Tube of 80	CD74HC595SM	HJ595
	330F - 3W	Reel of 2000	CD74HC595SM96	110090

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



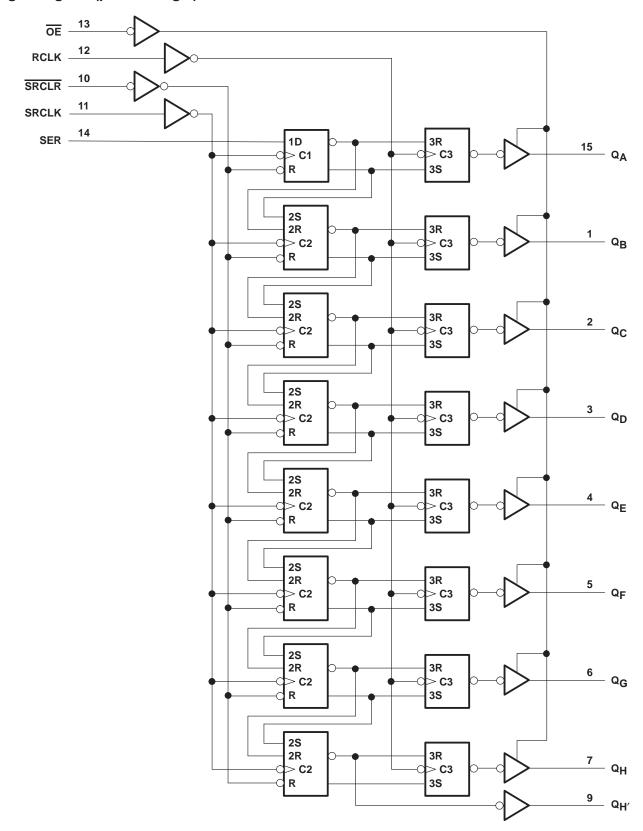
CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS SCHS353 - JANUARY 2004

FUNCTION TABLE

		INPUTS			FUNCTION
SER	SRCLK	SRCLR	RCLK	OE	FUNCTION
Х	Х	Х	Х	Н	Outputs Q _A –Q _H are disabled.
Х	Χ	Χ	Χ	L	Outputs Q _A –Q _H are enabled.
Х	Χ	L	Χ	Χ	Shift register is cleared.
L	1	Н	Х	Х	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
Н	1	Н	Х	Х	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
Х	Х	Х	1	Χ	Shift-register data is stored in the storage register.



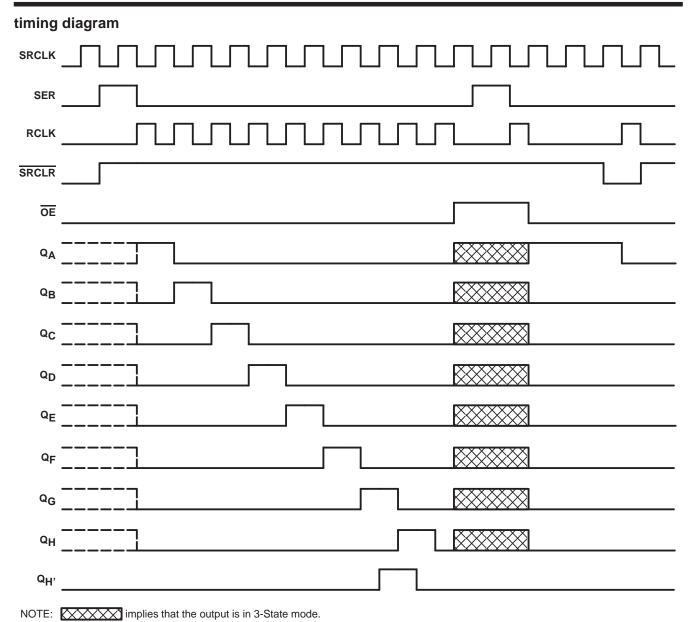
logic diagram (positive logic)





CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	C) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	-	±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ _{JA} (see Note 2)	: E package	67°C/W
	DW package	57°C/W
	M package	73°C/W
	NS package	64°C/W
	SM package	82°C/W
Storage temperature range, T _{stg}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	V
		V _{CC} = 2 V	1.5			
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			V
		$V_{CC} = 6 V$	4.2			
		V _{CC} = 2 V			0.5	
VIL	V _{IL} Low-level input voltage	V _{CC} = 4.5 V			1.35	V
		VCC = 6 V			1.8	
VI	Input voltage		0		VCC	V
VO	Output voltage		0		VCC	V
		V _{CC} = 2 V			1000	
Δt/Δv‡	Input transition rise/fall time	V _C C = 4.5 V			500	ns
		VCC = 6 V			400	
TA	Operating free-air temperature		-55		125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



[‡] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

CD74HC595 8-BIT SHIFT REGISTERS WITH 3-STATE OUTPUT REGISTERS SCHS353 - JANUARY 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TES-	r conditions	vcc	Т	A = 25°C	;	T _A = -55		T _A = -40 85°		UNIT	
				MIN	TYP	MAX	MIN	MAX	MIN	MAX		
			2 V	1.9	1.998		1.9		1.9			
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4			
VOH VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9				
	$Q_{H'}$, $I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		V		
		$Q_A - Q_H$, $I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84			
		$Q_{H'}$, $I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34			
		$Q_{A}-Q_{H}$, $I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34			
			2 V		0.002	0.1		0.1		0.1		
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1		
				6 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL	$Q_{H'}$, $I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V	
		Q_A-Q_H , $I_{OL}=6$ mA	4.5 V		0.17	0.26		0.4		0.33		
		$Q_{H'}$, $I_{OL} = 5.2 \text{ mA}$	6.17		0.15	0.26		0.4		0.33		
		Q_A-Q_H , $I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33		
ΙĮ	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA	
loz	$V_O = V_{CC}$ or 0,	Q_A-Q_H	6 V		±0.01	±0.5		±10		±5	μΑ	
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ	
Ci			2 V to 6 V		3	10		10		10	pF	



timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			v _{cc}	T _A = 1	25°C	T _A = -55		T _A = -40		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		29	
			2 V	80		120		100		
		SRCLK or RCLK high or low	4.5 V	16		24		20		
	Dodge down Con		6 V	14		20		17		
t_W	Pulse duration		2 V	80		120		100		ns
		SRCLR low	4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	100		150		125		
		SER before SRCLK↑	4.5 V	20		30		25		
			6 V	17		25		21		
			2 V	75		113		94		
		SRCLK↑ before RCLK↑†	4.5 V	15		23		19		
	0:		6 V	13		19		16		
t _{su}	Setup time		2 V	50		75		65		ns
		SRCLR low before RCLK↑	4.5 V	10		15		13		
			6 V	9		13		11		
			2 V	50		75		60		
		SRCLR high (inactive) before SRCLK↑	4.5 V	10		15		12		
			6 V	9		13		11		
			2 V	0		0		0		
th	Hold time, SER a	fter SRCLK↑	4.5 V	0		0		0		ns
			6 V	0		0		0		

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	Vcc	T,	Δ = 25°C	;	T _A = -55		T _A = -40		UNIT			
	(INPUT)	(001701)		MIN	TYP	MAX	MIN	MAX	MIN	MAX				
			2 V	6	26		4.2		5					
fmax			4.5 V	31	38		21		25		MHz			
			6 V	36	42		25		29					
			2 V		50	160		240		200				
	SRCLK	$Q_{H'}$	4.5 V		17	32		48		40				
4 .			6 V		14	27		41		34				
^t pd			2 V		50	150		225		187	ns			
	RCLK	Q_A – Q_H	4.5 V		17	30		45		37				
			6 V		14	26		38		32				
			2 V		51	175		261		219				
t _{PHL}	SRCLR	$Q_{H'}$	4.5 V		18	35		52		44	ns			
			6 V		15	30		44		37				
			2 V		40	150		225		187				
t _{en}	ŌĒ	Q _A -Q _H	4.5 V		15	30		45		37	ns			
			6 V		13	26		38		32				
			2 V		42	200		300		250				
^t dis	ŌĒ	Q_A – Q_H	Q_A-Q_H	Q_A – Q_H	Q_A – Q_H	4.5 V		23	40		60		50	ns
			6 V		20	34		51		43				
			2 V		28	60		90		75				
		Q _A –Q _H	4.5 V		8	12		18		15				
			6 V		6	10		15		13				
t _t			2 V		28	75		110		95	ns			
		$Q_{H'}$	4.5 V		8	15		22		19				
			6 V		6	13		19		16				

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

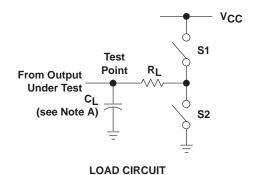
PARAMETER	FROM	TO (OUTPUT)	VCC	T	λ = 25°C	;	T _A = -55		T _A = -40 85°		UNIT	
	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX		
			2 V		60	200		300		250		
t _{pd}	RCLK	Q _A -Q _H	4.5 V		22	40		60		50	ns	
			6 V		19	34		51		43		
			2 V		70	200		298		250		
t _{en}	ŌĒ	Q _A -Q _H	4.5 V		23	40		60		50	ns	
			6 V		19	34		51		43		
			2 V		45	210		315		265		
t _t		Q _A –Q _H	Q _A –Q _H	4.5 V		17	42		63		53	ns
			6 V		13	36		53		45		

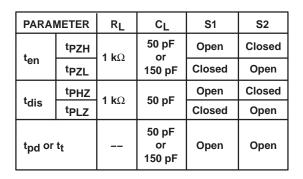


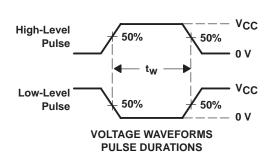
operating characteristics, $T_A = 25^{\circ}C$

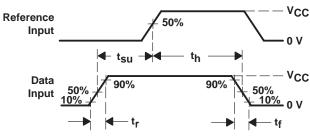
PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load	400	pF

PARAMETER MEASUREMENT INFORMATION

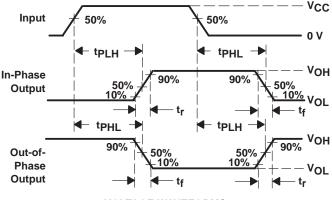


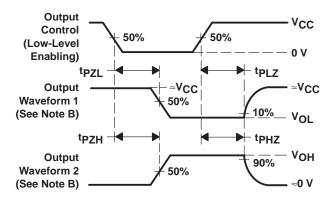






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - E. The outputs are measured one at a time, with one input transition per measurement.
 - F. tpLz and tpHz are the same as tdis.
 - G. tpzL and tpzH are the same as ten.
 - H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
	(1)		J		,	(2)	(6)	(6)		(40)	
CD74HC595DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC595M	Samples
CD74HC595DWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC595M	Samples
CD74HC595E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC595E	Samples
CD74HC595EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC595E	Samples
CD74HC595M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC595M	Samples
CD74HC595M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC595M	Samples
CD74HC595MG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC595M	Samples
CD74HC595MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC595M	Samples
CD74HC595NSR	ACTIVE	so	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC595M	Samples
CD74HC595SM96	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ595	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: Til defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

10-Dec-2020

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All differsions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC595DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
CD74HC595M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC595NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC595SM96	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC595DWR	SOIC	DW	16	2000	350.0	350.0	43.0
CD74HC595M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HC595NSR	SO	NS	16	2000	853.0	449.0	35.0
CD74HC595SM96	SSOP	DB	16	2000	853.0	449.0	35.0

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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